

Electronic Acknowledgement Receipt

EFS ID:	8984593
Application Number:	10710596
International Application Number:	
Confirmation Number:	4595
Title of Invention:	[CHIP STRUCTURE WITH A PASSIVE DEVICE AND METHOD FOR FORMING THE SAME]
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Patricia Balero
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0101
Receipt Date:	07-DEC-2010
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Time Stamp:	16:32:58
Application Type:	Utility under 35 USC 111(a)

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureStatement1-085027-0101.pdf	200930 1b24de7807fd9b2ddd591cfad37d33845b3 76dc3	no	9

Warnings:

Information:

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2	Foreign Reference	EP0683519_FRN00291.pdf	1857931 479d15286ed9ee334cf82264612e53fdb5 b110a	no	30
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3	Foreign Reference	EP0884783_FRN00010.pdf	778835 626f6ce854f9b81ed94856775e04ad40c21a 3552	no	12
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4	Foreign Reference	EP0986106_FRN00011.pdf	1309605 0fe956e933611e3dc0d81412cd33fdfa5083 8c06	no	28
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5	Foreign Reference	EP0999580_FRN00012.pdf	619510 2201a6388c967a1b569d6b4486f6f3d2952 5e9db	no	13
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6	Foreign Reference	FR2793943_FRN00008.pdf	1253733 21f0dadba06abcf64481b730ff587c36fe970 05c	no	22
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7	Foreign Reference	JP03019358_FRN00013.pdf	521080 f43373f48b395f9c36738f3097fd7b526ab31 d67	no	7
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8	Foreign Reference	JP2000022085_FRN00014.pdf	595691 b0a5333c60d7bc2ab0fa5bd5750af06f5b1 7f98	no	9
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9	Foreign Reference	TW232078.pdf	1104540 32bcd9d7845abd46ae0d074051fc2878787 b1a18	no	18
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11	Foreign Reference	TW466745_FRN00311_pdf.pdf	771183 c7c3c56fb9908c1c9e295f2369e54bc3362 1a2c	no	22
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13	Foreign Reference	TW489346_FRN00310_pdf.pdf	4837730 84bc72b2d1b88a5f9763aac06fd10639016 a7bba	no	44
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14	Foreign Reference	TW497250_FRN00288_pdf.pdf	1672719 8df052d428f5df11009dd344163759975ae 6547f	no	24
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20	Foreign Reference	WO2000004577_FRN00312.pdf	1334817 30a7b364cc83960574c4058f76b66abb5f 85bcd	no	33
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21	NPL Documents	BURGHARTZ_Spiral_Inductors_and_Transmission_Lines_in_Silicon_Technology.pdf	680366 425087aeb45deadc902285ae2636e3e017c 1365e	no	8
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22	NPL Documents	YIM_The_Effects_of_a_Ground_Shield_on_Spiral_Inductors.pdf	334945 3b42549886f1bae1e7a0686ec93a86fb2 d909d	no	4
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23	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureStatement2-085027-0101.pdf	184155 38be48a544c171bf2cbf230e515615ed857 6e43a	no	5
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24	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 072127b124142b87d48b36305577e00d7f2 81092	no	4
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25	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109 da31204b1d9d203a708a79ef619df46550 68f74	no	9
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26	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a340bcb7c9b1547370da4bc4129a0cd8aa aeb74	no	7
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28	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6ea9c2af4c3f93c0d5e8d84fcc64bb8318ee e28a	no	5
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29	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f30badcc448865be25da92121b117fce2 67a05	no	7
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30	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8132037f7462423e7e041a4f39e24a5e4578 ab27	no	8
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31	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726022251835f4d292326de7bc282d5944 1d614	no	4
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32	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab71bc6a4d8720a9b8f6ef9476e4dc5e395 eebb5	no	4
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33	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 9501660bd4c4309f18b1797ed0026a7b2bc 14322	no	4
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34	NPL Documents	11_VENKATESAN_A_High_performance_1_8V.pdf	618169 7bc331a4bbe29891fc13105b6c5bc7609f2c 568d	no	4
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35	NPL Documents	12_JENEI_HighQInductors.pdf	279415 1749e7bd1f20e8e3cceb6d074bc37238ecf b831	no	3
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36	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BiCMOS_process.pdf	420788 8e26f2f669459e3ce07d15bd587c4a335999 fa0e	no	4
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37	NPL Documents	14_SAKRAN_implementation_of_65nm.pdf	1254646 3b466954664fc7184e733083637d22ae0 8c5a1	no	3
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38	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c0afeda905c311c1fc91a55df92d1793f8f43 7f	no	2
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39	NPL Documents	16_BOHR_presentation_Intel_ISSCC_09_plenary.pdf	8968148 288c45398d711068a36020473b6c927da65 28428	no	66
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43	NPL Documents	20_PDF_MALONEY_Novel_clamp_circuits_for_IC_power_supply_protection_pdf.pdf	191082 d68b46b342e836f0eda7955b62f7276a63e 41cd7	no	12
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44	NPL Documents	21_PDF_GEFFKEN_Overview_of_polymide_pdf.pdf	851514 e18b14453fb0b5d803d7a37663977c5306a b7dea	no	11
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45	NPL Documents	22_PDF_LUTHER_Planar_Copper_pdf.pdf	2095781 90afdb29bd75e9d46783563e765b92e1c2d6 87a5a	no	8
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46	NPL Documents	23_PDF_MASTER_Ceramic_Ball _Grid_Array_pdf.pdf	1069512 bd6eee156a9033c17b7766d18810a6d0f3 58a0b	no	5
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47	NPL Documents	24_PDF_MALONEY_Stacked_P MOS_clamps_for_high_voltage _power_supply_protection_pd f_pdf.pdf	1327621 bf7256b30d3890a26269a1501436f32580e bde88	no	8
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48	NPL Documents	25_PDF_LIN_A_New_System_ On_Chip_Technology_pdf.pdf	390082 420f653cae0b51f8d846f872b9a351e6fa 4296	no	7
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49	NPL Documents	26_PDF_MEGICA_Brochure_lea flets_01_28_04_pdf.pdf	888383 aec89db5e67eb17d33ea9f52144d8fbcc181f fd9a	no	3
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50	NPL Documents	27_PDF_LIN_Post_Passivation Technology_Presentation_for_ TSMC_Tech_Symposium_2003 _pdf.pdf	1277639 20556e2754a2807cec285bcc5d87f24d527 17e89	no	32
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51	NPL Documents	28_PDF_LIN_A_New_IC_Interc onnection_Scheme_and_Desig n_pdf.pdf	116206 e1ef1d6bb5ccf0007c76b6677a40a8a47106 eecb8	no	4
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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.